

TOSHIBA

TOSHIBA Original CMOS 8-Bit Microcontroller

TLCS-870 Series

TMP87PH48UG

TMP87PH48DFG

TMP87PM48UG

TMP87PM48DFG

Not Recommended
for New Design

TOSHIBA CORPORATION

Semiconductor Company

Important Notices

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This page gives you important information on using Toshiba microcontrollers. Please be sure to check each item for proper use of our products.

Not Recommended
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TOSHIBA Microcontrollers**870 Family****(TMP87CH48U) (TMP87CH48DF) (TMP87CM48U) (TMP87CM48DF) (TMP87CH48I)****(TMP87PH48U) (TMP87PH48DF) (TMP87PM48U) (TMP87PM48DF)****Datasheet Modifications: I²C Bus Mode Control**

The following problem is included in the explanation of the I²C bus function of this data sheet.
It will guide the correction as follows. Please read it for the explanation of this data sheet as follows.

Section: "I²C Bus Mode Control"**▪ In the explanation of the Serial Bus Interface Control Register 1**

1. Delete the setting examples where the serial clock frequency exceeds 100 kHz.
2. Add the following note.

SCK	Serial clock selection	000 : Reserved	(Note)	} at f _c = 8MHz (Output on SCL pin)	Write-only
		001 : Reserved	(Note)		
		010 : 58.8	kHz		
		011 : 30.3	kHz		
		100 : 15.4	kHz		
		101 : 7.75	kHz		
		110 : 3.89	kHz		
		111 : reserved			

Note: This I²C bus circuit does not support the Fast mode. It supports the Standard mode only. Although the I²C bus circuit itself allows the setting of a baud rate over 100 kbps, the compliance with the I²C specification is not guaranteed in that case.

▪ In "(3) Serial clock"

1. Add the following sentence about the communication baud rate.

a. Clock source

The SCK (bits 2 to 0 in the SBICR1) is used to select a maximum transfer frequency outputed on the SCL pin in the master mode. **Set a communication baud rate that meets the I²C bus specification, such as the shortest pulse width of t_{LOW}, based on the equations shown below.**

In both master mode and slave mode, a pulse width of at least 4 machine cycles is require for both "H" and "L" levels.

$$t_{LOW} = 2^n / f_c$$

$$t_{HIGH} = 2^n / f_c + 8 / f_c$$

$$f_{scl} = 1 / (t_{LOW} + t_{HIGH})$$

Document Change Notification

The purpose of this notification is to inform customers about the launch of the Pb-free version of the device. The introduction of a Pb-free replacement affects the datasheet. Please understand that this notification is intended as a temporary substitute for a revision of the datasheet.

Changes to the datasheet may include the following, though not all of them may apply to this particular device.

1. Part number

Example: TMPxxxxxxF TMPxxxxxxFG

All references to the previous part number were left unchanged in body text. The new part number is indicated on the prelims pages (cover page and this notification).

2. Package code and package dimensions

Example: LQFP100-P-1414-0.50C LQFP100-P-1414-0.50F

All references to the previous package code and package dimensions were left unchanged in body text. The new ones are indicated on the prelims pages.

3. Addition of notes on lead solderability

Now that the device is Pb-free, notes on lead solderability have been added.

4. RESTRICTIONS ON PRODUCT USE

The previous (obsolete) provision might be left unchanged on page 1 of body text. A new replacement is included on the next page.

5. Publication date of the datasheet

The publication date at the lower right corner of the prelims pages applies to the new device.

1. Part number
2. Package code and dimensions

Previous Part Number (in Body Text)	Previous Package Code (in Body Text)	New Part Number	New Package Code	OTP
TMP87PH48U	P-LQFP64-1010-0.50	TMP87PH48UG	LQFP64-P-1010-0.50E	—
TMP87PH48DF	P-QFP64-1414-0.80A	TMP87PH48DFG	QFP64-P-1414-0.80C	—
TMP87PM48U	P-LQFP64-1010-0.50	TMP87PM48UG	LQFP64-P-1010-0.50E	—
TMP87PM48DF	P-QFP64-1414-0.80A	TMP87PM48DFG	QFP64-P-1414-0.80C	—

*: For the dimensions of the new package, see the attached Package Dimensions diagram.

3. Addition of notes on lead solderability

The following solderability test is conducted on the new device.

Lead solderability of Pb-free devices (with the G suffix)

Test	Test Conditions	Remark
Solderability	(1) Use of Lead (Pb) ·solder bath temperature = 230°C ·dipping time = 5 seconds ·the number of times = once ·use of R-type flux (2) Use of Lead (Pb)-Free ·solder bath temperature = 245°C ·dipping time = 5 seconds ·the number of times = once ·use of R-type flux	Leads with over 95% solder coverage till lead forming are acceptable.

4. RESTRICTIONS ON PRODUCT USE

The following replaces the “RESTRICTIONS ON PRODUCT USE” on page 1 of body text.

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20070701-EN

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5. Publication date of the datasheet

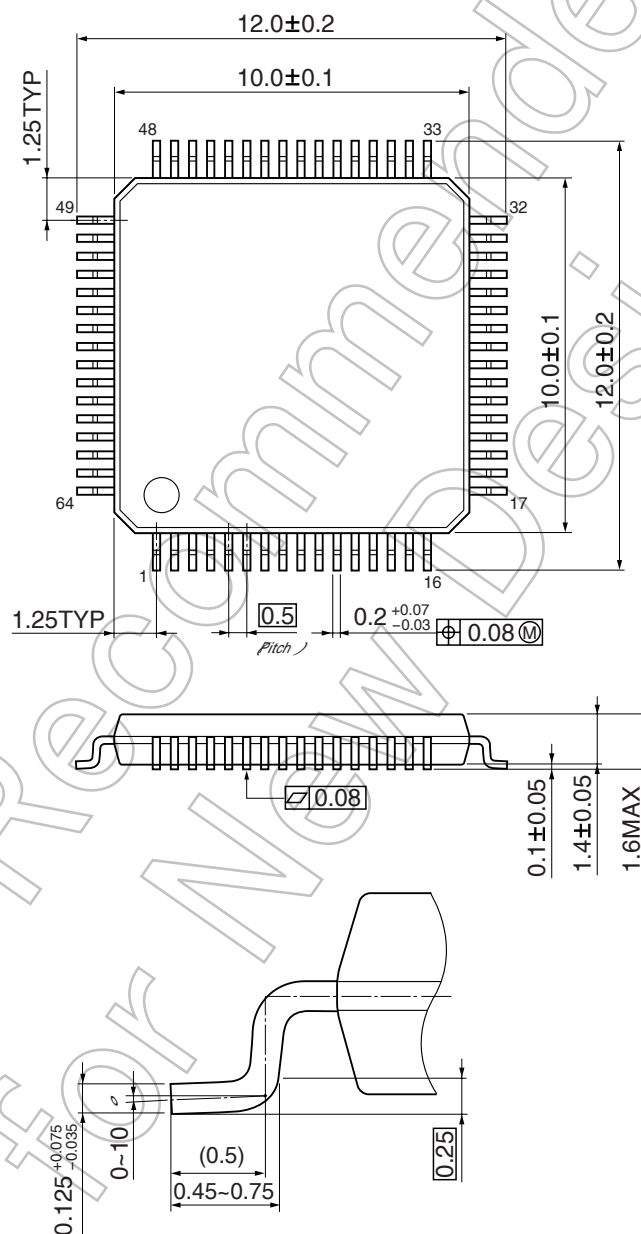
The publication date of this datasheet is printed at the lower right corner of this notification.

(Annex)

Package Dimensions

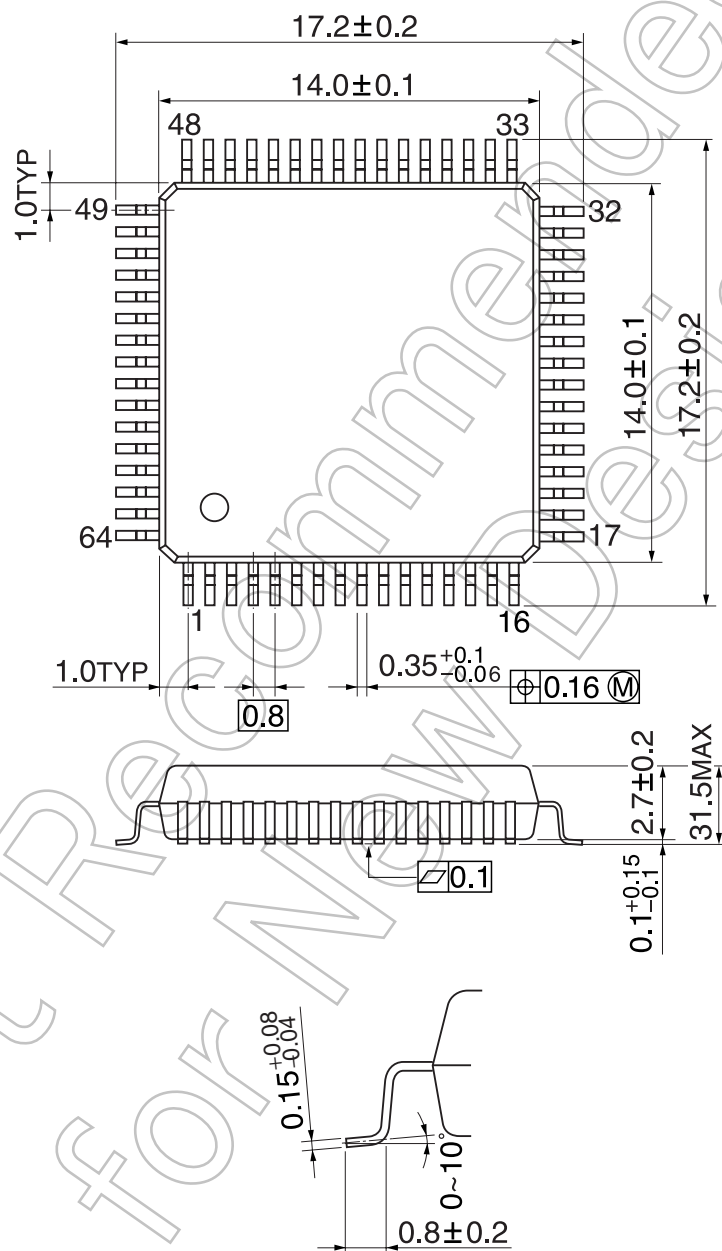
LQFP64-P-1010-0.50E

Unit: mm



QFP64-P-1414-0.80C

Unit: mm



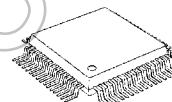
CMOS 8-Bit Microcontroller

TMP87PH48U/DF, TMP87PM48U/DF

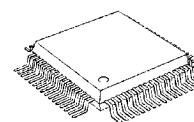
The TMP87PH48 is a one-time PROM microcontroller with low-power 128 Kbits (16 Kbytes) electrically programmable read only memory for the TMP87CH48 system evaluation. The TMP87PM48 is a One-time PROM microcontroller with low-power 256 Kbits (32 Kbytes) electrically programmable read only memory for the TMP87CM48 system evaluation. The TMP87PH48/PM48 are pin compatible with the TMP87CH48/CM48. The operations possible with the TMP87CH48/CM48 can be performed by writing programs to PROM. The TMP87PH48/PM48 can write and verify in the same way as the TC57256AD using an adaptor sockets BM11117/BM11147 and an EPROM programmer.

Product No.	ROM	RAM	Package	Adapter Socket
TMP87PH48U	16 K × 8 bits	512 × 8 bits	P-LQFP64-1010-0.50	BM11117
TMP87PH48DF			P-QFP64-1414-0.80A	BM11147
TMP87PM48U	32 K × 8 bits	1 K × 8 bits	P-LQFP64-1010-0.50	BM11117
TMP87PM48DF			P-QFP64-1414-0.80A	BM11147

P-LQFP64-1010-0.50

TMP87PH48U
TMP87PM48U

P-QFP64-1414-0.80A

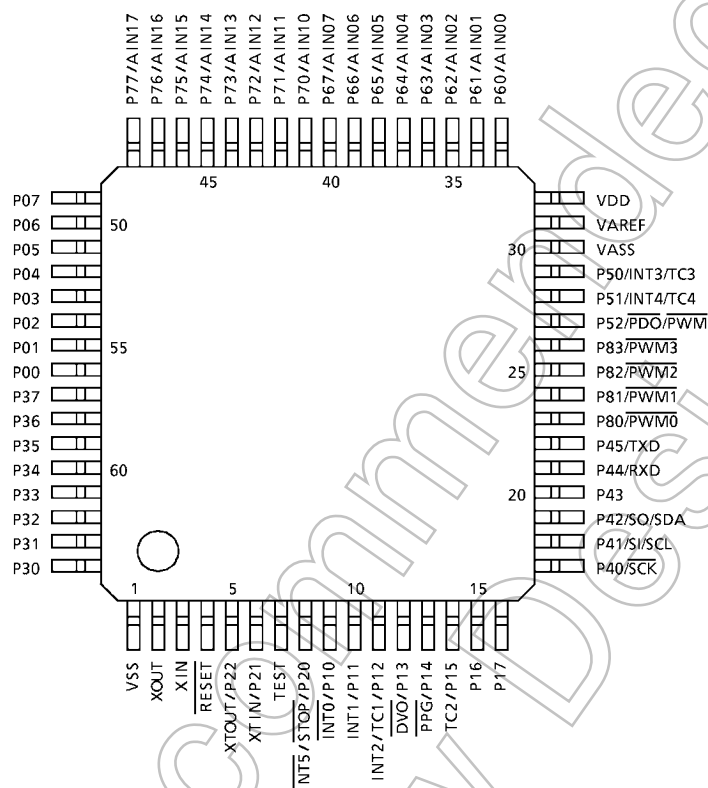
TMP87PH48DF
TMP87PM48DF

030619EBP2

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Pin Assignments (Top View)

P-LQFP64-1010-0.50
P-QFP64-1414-0.80A



Pin Function

The TMP87PH48/PM48 have two modes: MCU and PROM.

(1) MCU mode

In this mode, the TMP87PH48/PM48 are pin compatible with the TMP87CH48/CM48 (Fix the TEST pin at low level).

(2) PROM mode

Pin Name (PROM mode)	Input/Output	Functions	Pin Name (MCU mode)	
A14 to A8	Input	PROM address inputs	P76 to P70	
A7 to A0			P81, P80, P45 to P40	
D7 to D0	I/O	PROM data input/outputs	P07 to P00	
\overline{CE}	Input	Chip enable signal input (active low)	P13	
\overline{OE}		Output enable signal input (active low)	P14	
VPP	Power supply	+ 12.5 V/5 V (Program supply voltage)	TEST	
VCC		+ 5 V	VDD	
GND		0 V	VSS	
P37 to P34	I/O	Open		
P32 to P30		Pull-up with resistance R1 for input processing		
P52 to P50				
P83, P82				
P67 to P60				
P11, P12, P15	I/O	PROM mode setting pins. Be fixed at high level. (Pull-up with resistance R2)		
P21				
P77				
P17, P16, P10		PROM mode setting pins. Be fixed at low level.		
P133				
P22, P20				
RESET				
XIN	Input	Connect an 8 MHz oscillator to stabilize the internal state.		
XOUT	Output			
VAREF	Power Supply	0 V (GND)		
VASS				

Operational Description

The following explains the TMP87PH48/PM48 hardware configuration and operation. The configuration and functions of the TMP87PH48/PM48 are the same as those of the TMP87CH48/CM48, except in that a one-time PROM is used instead of an on-chip mask ROM.

The TMP87PH48/PM48 are placed in the *single-clock* mode during reset. To use the dual-clock mode, the low-frequency oscillator should be turned on by executing [SET (SYSCR2). XTEN] instruction at the beginning of the program.

1. Operating Mode

The TMP87PH48/PM48 have two modes: MCU and PROM.

1.1 MCU Mode

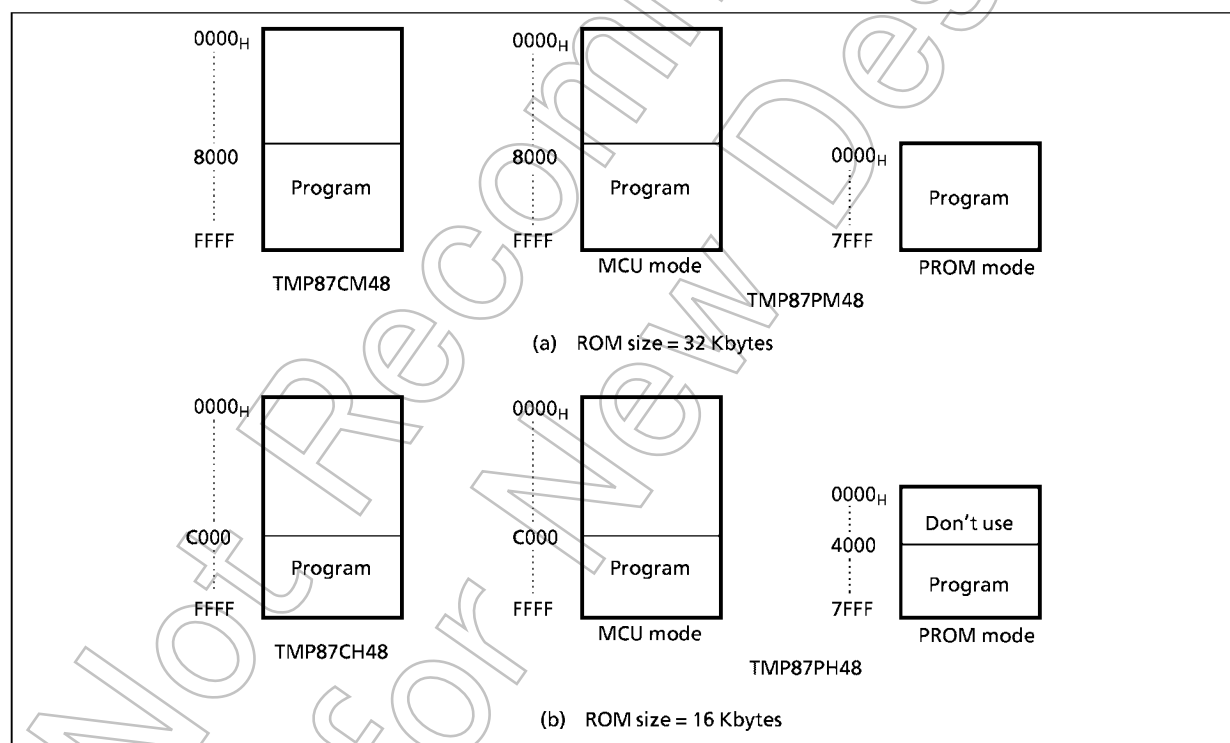
The MCU mode is activated by fixing the TEST/VPP pin at low level.

In the MCU mode, operation is the same as with the TMP87CH48/CM48 (The TEST/VPP pin cannot be used open because TMP87PH48/PM48 have no built-in pull-down resistance).

1.1.1 Program Memory

The TMP87PH48/PM48 have a 16K × 8-bit (Addresses C000_H to FFFF_H in the MCU mode, addresses 4000_H to 7FFF_H in the PROM mode) the TMP87PM48 has a 32K × 8 bit (Address 8000_H to FFFF_H in the MCU mode, addresses 0000_H to 7FFF_H in the PROM mode) of program memory (OTP).

To use the TMP87PH48/PM48 as the system evaluation for the TMP87CH48/CM48, the program should be written to the program memory area as shown in Figure 1-1.



Note: Either write the data FF_H to the unused area or set the PROM programmer to access only the program storage area.

1.1.2 Data Memory

The TMP87PH48 have an on-chip 512×8 -bit data memory (Static RAM).

The TMP87PM48 have an on-chip $1K \times 8$ -bit data memory (Static RAM).

1.1.3 Input/Output Circuitry

(1) Control pins

The control pins of the TMP87PH48/PM48 are the same as those of the TMP87CH48/CM48 except that the TEST pin has no built-in pull-down resistance.

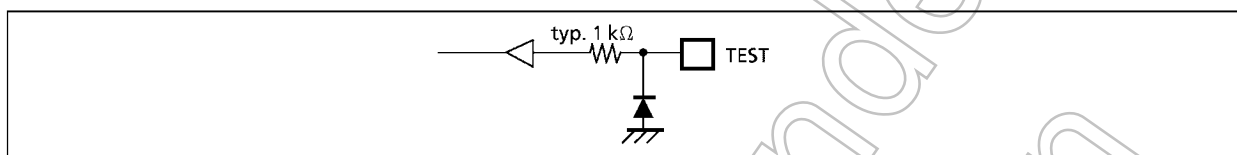


Figure 1-2. TEST Pin

(2) I/O ports

The I/O circuitries of TMP87PH48/PM48 I/O ports are the same as the TMP87CH48/CM48.

1.2 PROM Mode

The PROM mode is activated by setting the TEST, $\overline{\text{RESET}}$ pin and the ports P17 to P10, P22 to P20 and P77 as shown in Figure 1-3. The PROM mode is used to write and verify programs with a general-purpose PROM programmer.

The high-speed programming mode can be used for program operation.
The TMP87PH48/PM48 are not supported an *electric signature* mode, so the ROM type must be set to TC57256AD AD.

Set the adaptor socket switch to "N".

Note: Please set the high-speed programming mode according to each manual of PROM programmer.

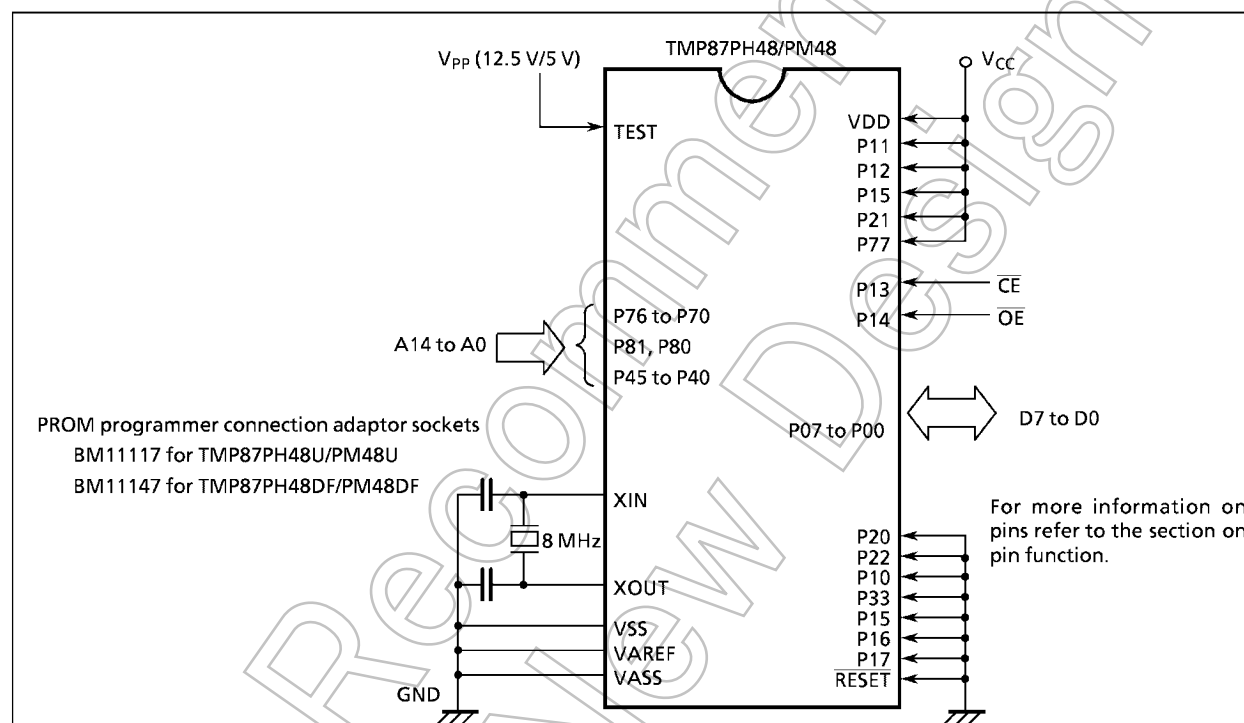


Figure 1-3. Setting for PROM Mode

1.2.1 Programming Flowchart (High-speed programming mode-I)

The high-speed programming mode is achieved by applying the program voltage (+ 12.5 V) to the Vpp pin when Vcc = 6 V. After the address and input data are stable, the data is programmed by applying a single 1ms program pulse to the CE input. The programmed data is verified. If incorrect, another 1ms program pulse is applied and then the programmed data is verified. This process should be repeated (Up to 25 times) until the program operates correctly. Programming for one address is ended by applying additional program pulse with width 3 times that needed for initial programming (Number of programmed times × 1 ms). After that, change the address and input data, and program as before. When programming has been completed, the data in all addresses should be verified with Vcc = Vpp = 5 V.

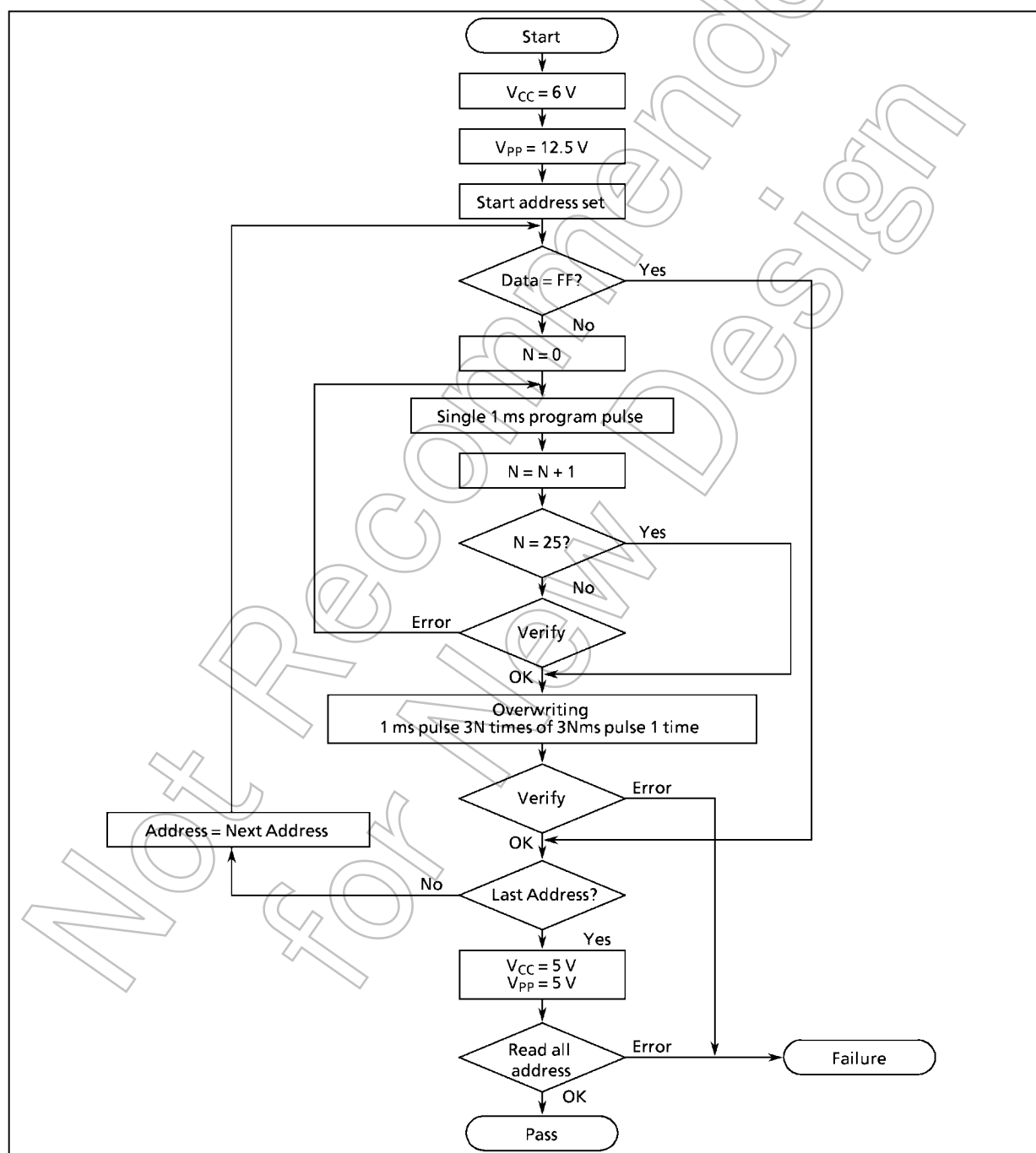


Figure 1-4. Flowchart of High-speed Programming Mode - I

1.2.2 Programming Flowchart (High-speed programming mode-II)

The high-speed programming mode is achieved by applying the program voltage (+ 12.75 V) to the Vpp pin when Vcc = 6.25 V. After the address and input data are stable, the data is programmed by applying a single 0.1ms program pulse to the \overline{CE} input. The programmed data is verified. If incorrect, another 0.1ms program pulse is applied and then the programmed data is verified. This process should be repeated (Up to 25 times) until the program operates correctly. After that, change the address and input data, and program as before. When programming has been completed, the data in all addresses should be verified with Vcc = Vpp = 5 V.

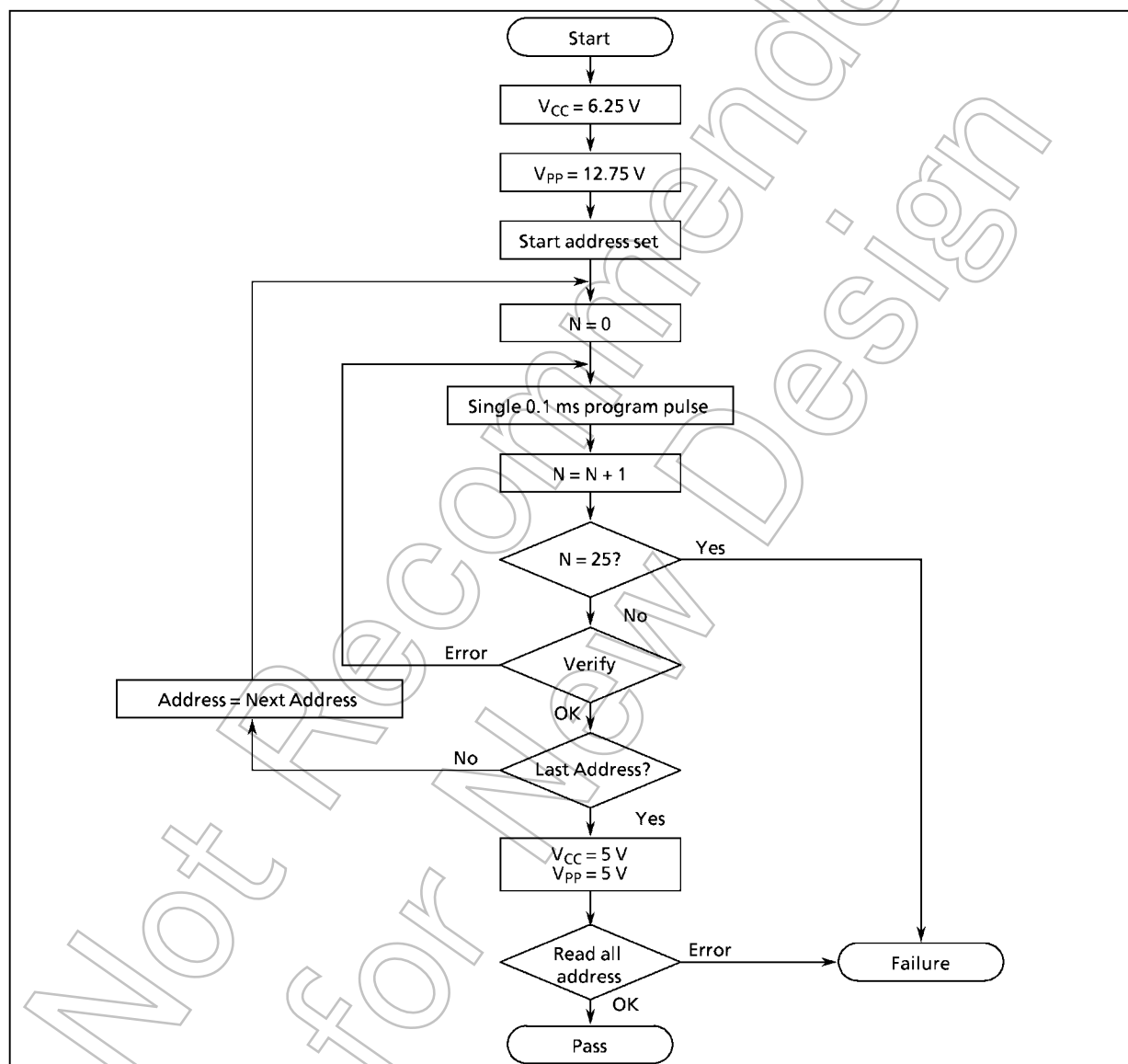


Figure 1-5. Flowchart of High-speed Programming Mode - II

1.2.3 Writing Method for General-purpose PROM Program

(1) Adapters

BM11117: TMP87PH48U, TMP87PM48U

BM11147: TMP87PH48DF, TMP87PM48DF

(2) Adapter setting

Switch (SW1) is set to side N.

(3) PROM programmer specifying

i) PROM type is specified to TC57256AD.

Writing voltage: 12.5 V (High-speed program I mode)

12.75 V (High-speed program II mode)

ii) Data transfer (Copy) (Note 1)

In TMP87PH48, EPROM is within the addresses 4000 to 7FFFH. In TMP87PM48, EPROM is within the addresses 0000 to FFFFH. Data is required to be transferred (Copied) to the addresses where it is possible to write. The program area in MCU mode and PROM mode is referred to "Program memory area" in figure 1-1.

Ex. In the block transfer (Copy) mode, executed as below.

ROM capacity of 16KB: transferred addresses C000 to FFFFH to addresses 4000 to 7FFFH

iii) Writing address is specified (Note 1)

TMP87PH48: Start address: 4000H

End address: 7FFFH

TMP87PM48: Start address: 0000H

End address: 7FFFH

(4) Writing

Writing/Verifying is required to be executed in accordance with PROM programmer operating procedure.

Note 1: The specifying method is referred to the PROM programmer description. The data in addresses 0000 to 3FFFH must be specified to FFH.

Note 2: When MCU is set to an adapter or the adapter is set to PROM programmer, a position of pin 1 must be adjusted. If the setting is reversed, MCU, the adapter and PROM program is damaged.

Note 3: TMP87PH48, TMP87PM48 don't support the electric signature mode (Hereinafter referred to as "signature"). If the signature is used in PROM program, a device is damaged due to applying 12V \pm 0.5V to the address pin 9 (A9). The signature must not be used.

Input/Output Circuitry

(1) Control pins

The input/output circuitries of the TMP87PH48/PM48 control pins are shown below.

Control Pin	I/O	Input/Output Circuitry	Remarks
XIN XOUT	Input Output		Resonator connecting pins (high-frequency) $R_f = 1.2\text{ M}\Omega$ (typ.) $R_o = 1.5\text{ k}\Omega$ (typ.)
XTIN XTOUT	Input Output		XTIN, XTOUT Resonator connecting pins (low-frequency) $R_f = 6\text{ M}\Omega$ (typ.) $R_o = 220\text{ k}\Omega$ (typ.) XTEN (Initial: 0) SW (XTEN = 0: OFF) (XTEN = 1: ON)
P21 P22	I/O I/O		P21, P22 Sink open drain output Hysteresis input $R = 1\text{ k}\Omega$ (typ.)
RESET	I/O		Sink open drain output Hysteresis input Pull-up resistor $R_{IN} = 220\text{ k}\Omega$ (typ.) $R = 1\text{ k}\Omega$ (typ.)
STOP/INT5 (P20)	I/O		Hysteresis input $R = 1\text{ k}\Omega$ (typ.)
TEST	Input		$R = 1\text{ k}\Omega$ (typ.)

Note 1: The TMP87PH48/PM48 don't have a pull-down resistor (R_{IN}) and a diode (D_1) for TEST pin.

Note 2: The TMP87PH48/PM48/CH48/CM48 are placed in the single-clock mode during reset.

(2) Input/Output Ports

The input/output circuitries of the TMP87PH48/PM48 input/output ports are shown below.

Port	I/O	Input/Output Circuitry	Remarks
P0 P6 P7 P8	I/O		Tri-state I/O Initial "High-Z" R = 1 k Ω (typ.)
P1	I/O		Tri-state I/O Initial "High-Z" Hysteresis input R = 1 k Ω (typ.)
P3	I/O		High current output only P3 Sink open drain output Initial "High-Z" R = 1 k Ω (typ.)
P4 P5	I/O		Sink open drain output Initial "High-Z" Hysteresis input R = 1 k Ω (typ.)

Electrical Characteristics

(1) TMP87PH48

Absolute Maximum Ratings

(V_{SS} = 0 V)

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage	V _{DD}		- 0.3 to 6.5	V
Input voltage	V _{IN}		- 0.3 to V _{DD} + 0.3	V
Output voltage	V _{OUT}		- 0.3 to V _{DD} + 0.3	V
Output current (Per 1 pin)	I _{OUT1}	Ports P0, P1, P2, P4, P5, P6, P7, P8	3.2	mA
	I _{OUT2}	Port P3	30	
Output current (Total)	Σ I _{OUT1}	Ports P0, P1, P2, P4, P5, P6, P7, P8	120	mA
	Σ I _{OUT2}	Port P3	120	
Power dissipation	PD		350	mW
Soldering temperature (Time)	T _{sld}		260 (10 s)	°C
Storage temperature	T _{stg}		- 55 to 125	°C
Operating temperature	T _{opr}		- 40 to 85	°C

Note: The absolute maximum ratings are rated values which must not be exceeded during operation, even for an instant. Any one of the ratings must not be exceeded. If any absolute maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no absolute maximum rating value will ever be exceeded.

Recommended Operating Conditions

(V_{SS} = 0 V, T_{opr} = - 40 to 85°C)

Parameter	Symbol	Pins	Conditions		Min	Max	Unit
Supply voltage	V _{DD}		f _c = 8 MHz	NORMAL1/2 modes	4.5	5.5	V
				IDLE1/2 modes			
			f _c = 4.2 MHz	NORMAL1/2 modes	2.7		
				IDLE1/2 modes			
			f _s = 32.768 kHz	SLOW mode	2.0		
				SLEEP mode			
	STOP mode						
Input high voltage	V _{IH1}	Except hysteresis input	V _{DD} ≥ 4.5 V		V _{DD} × 0.70	V _{DD}	V
	V _{IH2}	Hysteresis input			V _{DD} × 0.75		
	V _{IH3}		V _{DD} < 4.5 V	V _{DD} × 0.90			
Input low voltage	V _{IL1}	Except hysteresis input	V _{DD} ≥ 4.5 V		0	V _{DD} × 0.30	V
	V _{IL2}	Hysteresis input				V _{DD} × 0.25	
	V _{IL3}		V _{DD} < 4.5 V	V _{DD} × 0.10			
Clock frequency	f _c	XIN, XOUT	V _{DD} = 4.5 to 5.5 V	0.4	8.0	MHz	
			V _{DD} = 2.7 to 5.5 V		4.2		
	f _s	XTIN, XTOUT		30.0	34.0	kHz	

Note 1: The recommended operating conditions for a device are operating conditions under which it can be guaranteed that the device will operate as specified. If the device is used under operating conditions other than the recommended operating conditions (Supply voltage, operating temperature range, specified AC/DC values etc.), malfunction may occur. Thus, when designing products which include this device, ensure that the recommended operating conditions for the device are always adhered to.

Note 2: The condition of clock frequency is in NORMAL1/2 modes and IDLE1/2 modes.

DC Characteristics

(V_{SS} = 0 V, T_{opr} = -40 to 85°C)

Parameter	Symbol	Pins	Conditions	Min	Typ.	Max	Unit
Hysteresis voltage	V _{HS}	Hysteresis inputs	V _{DD} = 5.0 V	–	0.9	–	V
Input current	I _{IN1}	TEST	V _{DD} = 5.5 V V _{IN} = 5.5 V/0 V	–	–	± 2	μA
	I _{IN2}	Open drain ports, Tri-state ports					
	I _{IN3}	RESET, STOP					
Input resistance	R _{IN2}	RESET	V _{DD} = 5.0 V	100	220	450	kΩ
Output leakage current	I _{LO}	Sink open drain ports	V _{DD} = 5.5 V, V _{OUT} = 5.5 V	–	–	2	μA
		Tri-state ports	V _{DD} = 5.5 V, V _{OUT} = 5.5/0 V	–	–	± 2	
Output high voltage	V _{OH2}	Tri-state ports	V _{DD} = 4.5 V, I _{OH} = -0.7 mA	4.1	–	–	V
Output low voltage	V _{OL}	Except for XOUT and P3	V _{DD} = 4.5 V, I _{OL} = 1.6 mA	–	–	0.4	mA
Output low current	I _{OL3}	P3	V _{DD} = 4.5 V, V _{OL} = 1.0 V	–	20	–	mA
Supply current in NORMAL 1, 2 modes	I _{DD}		V _{DD} = 5.5 V V _{IN} = 5.3 V/0.2 V f _c = 8 MHz f _s = 32.768 kHz	–	4.5	5.5	mA
Supply current in IDLE 1, 2 modes				–	2.5	4.0	mA
Supply current in NORMAL 1, 2 modes			V _{DD} = 3.0 V, V _{IN} = 2.8 V/0.2 V V _{IN} = 4.19 MHz f _s = 32.768 kHz	–	1.75	3.0	mA
Supply current in IDLE 1, 2 modes				–	1.25	2.0	mA
Supply current in SLOW mode			V _{DD} = 3.0 V V _{IN} = 2.8 V/0.2 V f _s = 32.768 kHz	–	20	30	μA
Supply current in SLEEP mode				–	10	20	μA
Supply current in STOP mode			V _{DD} = 5.5 V V _{IN} = 5.3 V/0.2 V	–	0.5	10	μA

Note 1: Typical values show those at T_{opr} = 25°CNote 2: Input Current I_{IN1}, I_{IN3}: The current through resistor is not included, when the input resistor (pull-up or pull-down) is contained.Note 3: I_{DD} except for I_{REF}.

AD Conversion Characteristics

(V_{SS} = 0 V, V_{DD} = 2.7 to 5.5 V, T_{opr} = -40 to 85°C)

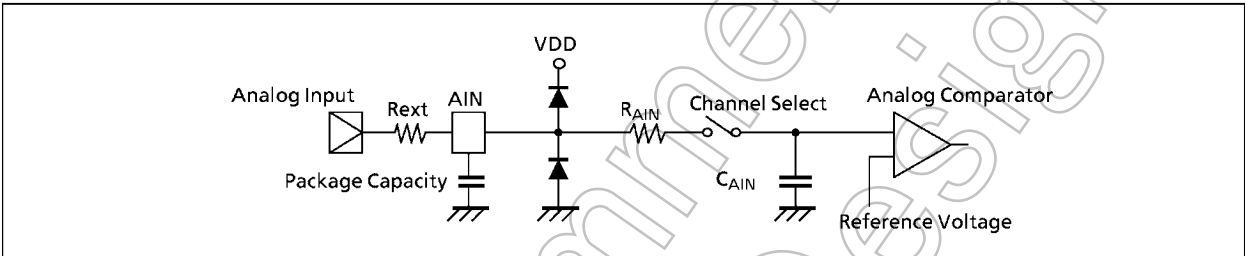
Parameter	Symbol	Conditions	Min	Typ.	Max			Unit
					ADCDR1	ADCDR2		
						ACK = 0	ACK = 1	
Analog reference voltage	V _{AREF}	V _{AREF} – V _{ASS} ≥ 2.5 V	2.7	–	V _{DD}			V
	V _{ASS}		V _{SS}	–	1.5			
Analog input voltage	V _{AIN}		V _{ASS}	–	V _{AREF}			V
Analog supply current	I _{REF}	V _{AREF} = 5.5 V, V _{ASS} = 0.0 V	–	0.5	1.2			mA
Nonlinearity error		V _{DD} = 5.0, V _{SS} = 0.0 V V _{AREF} = 5.000 V	–	–	± 1	± 3	± 2	LSB
Zero point error		V _{ASS} = 0.000 V or	–	–	± 1	± 3	± 2	
Full scale error		V _{DD} = 2.7, V _{SS} = 0.0 V V _{AREF} = 2.700 V	–	–	± 1	± 3	± 2	
Total error		V _{ASS} = 0.000 V	–	–	± 2	± 6	± 4	

Note 1: ΔV_{AREF} = V_{AREF} - V_{ASS}ADCDR1: 8 bits - AD conversion result (1LSB = ΔV_{AREF}/256)ADCDR2: 10 bits - AD conversion result (1LSB = ΔV_{AREF}/1024)

Note 2: Quantizing error is not contained in those errors.

AD Input Characteristics		(Topr = - 40 to 85°C)				
Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Input impedance (Resistance)	RAIN	VDD = 5.0 V, Conversion time 23 μs (fc = 8 MHz)	—	5	—	kΩ
		VDD = 2.7 V, Conversion time 43.8 μs (fc = 4.2 MHz)	—	20	—	
Input impedance (Capacity)	CAIN	VDD = 5.0 V, Conversion time 23 μs (fc = 8 MHz)	—	7	—	pF
		VDD = 2.7 V, Conversion time 43.8 μs (fc = 4.2 MHz)	—	7	—	
Source impedance	Rext	VDD = 5.0 V, Conversion time 23 μs (fc = 8 MHz)	—	—	5	kΩ
		VDD = 2.7 V, Conversion time 43.8 μs (fc = 4.2 MHz)	—	—	5	

Note: Input current (Output leak current) error (Max ± 2 μA) and quantizing error (Max ± 4LSB) for AD are contained.



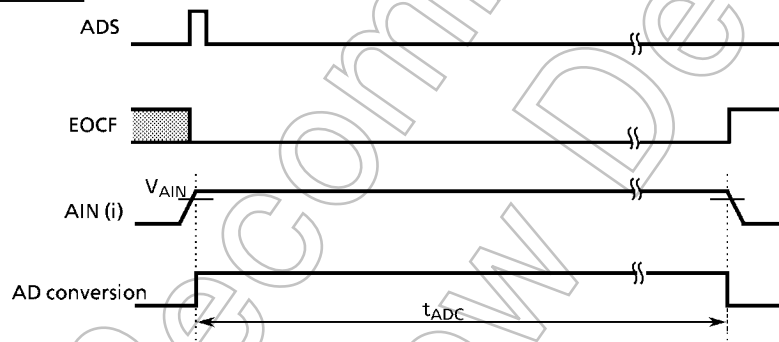
AD Pin Mode

AC Characteristics

 $(V_{SS} = 0\text{ V}, T_{opr} = -40\text{ to }85^{\circ}\text{C})$

Parameter	Symbol	Conditions	V_{DD}	Min	Typ.	Max	Unit
Machine cycle time	t_{cy}	In NORMAL 1, 2 mode	4.5 to 5.5 V	0.5	–	10	μs
		In IDLE 1, 2 mode					
		In SLOW mode	2.7 to 5.5 V	117.6	–	133.3	
		In SLEEP mode					
High level clock pulse width	t_{WCH}	For external clock operation (XIN input), $f_c = 8\text{ MHz}$	4.5 to 5.5 V	62.5	–	–	ns
Low level clock pulse width	t_{WCL}						
High level clock pulse width	t_{WSH}	For external clock operation (XTIN input), $f_s = 32.768\text{ kHz}$	2.7 to 5.5 V	14.7	–	–	μs
Low level clock pulse width	t_{WSL}						
AD conversion time	t_{ADC}	ADCCR bit 4; ACK = 0	–	–	49 t_{cy}	–	ns
		ADCCR bit 4; ACK = 1	–	–	196 t_{cy}	–	

Timing of AD Conversion

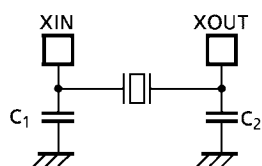


Note 1: During AD conversion, make the level of V_{AIN} stable.

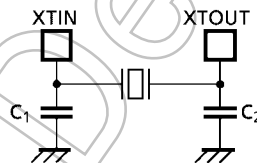
Note 2: $i = 17\text{ to }10, 07\text{ to }00$

Recommended Oscillating Conditions ($V_{SS} = 0\text{ V}$, $T_{opr} = -40\text{ to }85^{\circ}\text{C}$)

Parameter	Oscillator	Oscillation Frequency	VDD	Recommended Oscillator	Recommended Constant	
					C ₁	C ₂
High-frequency oscillation	Ceramic resonator	8 MHz	4.5 to 5.5 V	KYOCERA KBR8.0 M	30 pF	30 pF
		4 MHz	2.7 to 5.5 V	KYOCERA KBR4.0 M5		
				MURATA CSA4.00 MG		
	Crystal oscillator	8 MHz	4.5 to 5.5 V	TOYOCOM 210B 8.0000	20 pF	20 pF
		4 MHz	2.7 to 5.5 V	TOYOCOM 204B 4.0000		
Low-frequency oscillation	Crystal oscillator	32.768 kHz	2.7 to 5.5 V	NDK MX-38T	15 pF	15 pF



(1) High-frequency Oscillation



(2) Low-frequency Oscillation

Note 1: When it is used in high electrical field, an electrical shield of the package is recommended to retain normal operations.

Note 2: TOYAMA MURATA MFG. CO., LTD (JAPAN)

The product numbers and specifications of the resonators by Murata Manufacturing Co., Ltd. are subject to change.

For up-to-date information, please refer to the following URL;

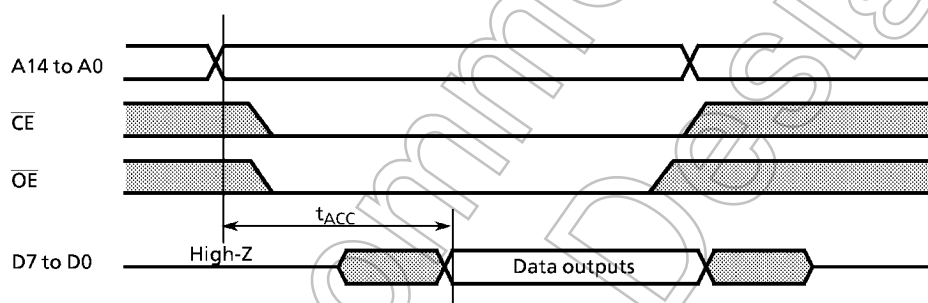
<http://www.murata.com/>

DC/AC Characteristics (PROM mode)

(V_{SS} = 0 V)

(1) Read operation

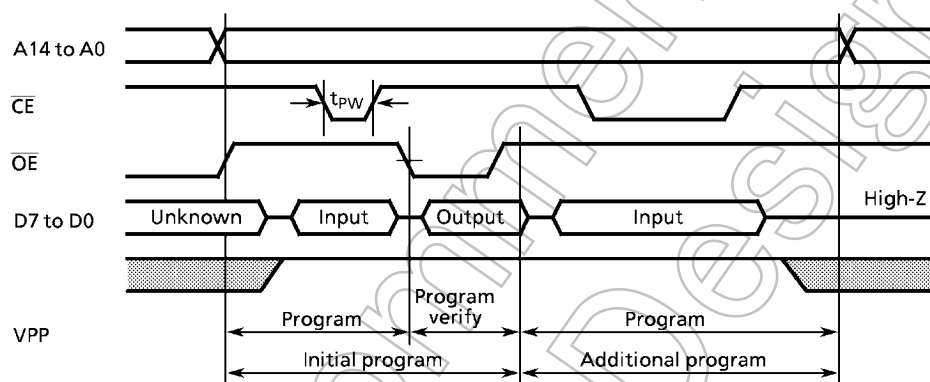
Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Input high voltage	V _{IH4}		2.2	–	V _{CC}	V
Input low voltage	V _{IL4}		0	–	0.8	V
Power supply voltage	V _{CC}		4.75	–	6.5	V
Program power supply voltage	V _{PP}					
Address access time	t _{ACC}	V _{CC} = 5.0 ± 0.25 V	–	1.5 t _{cy} + 300	–	ns

Note: t_{cy} = 500 ns at 8 MHz

Timing Waveforms of Read Operation

(2) Program Operation (High-speed write mode - I) (Topr = 25 ± 5°C)

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Input high voltage	V_{IH4}		2.2	—	V_{CC}	V
Input low voltage	V_{IL4}		0	—	0.8	V
Power supply voltage	V_{CC}		5.75	—	6.5	V
Program power supply voltage	V_{PP}		12.0	12.5	13.0	V
Initial program pulse width	t_{PW}	$V_{CC} = 6.0\text{ V} \pm 0.25\text{ V}$, $V_{PP} = 12.5\text{ V} \pm 0.5\text{ V}$	0.95	1.0	1.05	ms

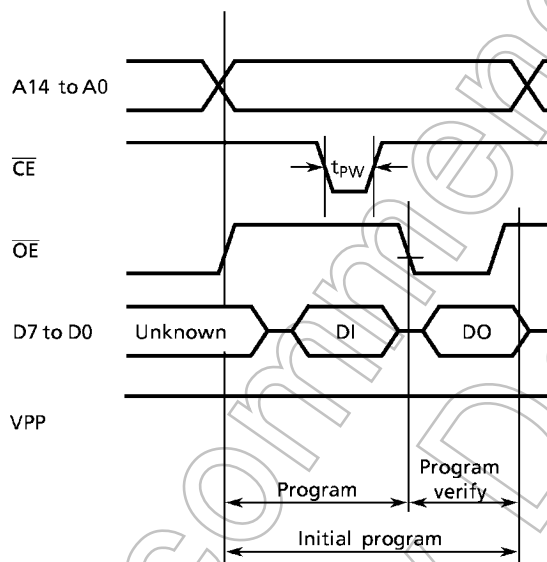


Timing Waveforms of Programming Operation

- Note 1:** When V_{CC} power supply is turned on or after, V_{PP} must be increased.
When V_{CC} power supply is turned off or before, V_{PP} must be decreased.
- Note 2:** The device must not be set to the EPROM programmer or picked up from it under applying the program voltage ($12.5\text{ V} \pm 0.5\text{ V}$) to the V_{PP} pin as the device is damaged.
- Note 3:** Be sure to execute the recommended programming mode with the recommended programming adaptor. If a mode or an adaptor except the above, the misoperation sometimes occurs.

(3) Program operation (High-speed write mode - II) ($T_{opr} = 25 \pm 5^{\circ}\text{C}$)

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Input high voltage	V_{IH4}		2.2	–	V_{CC}	V
Input low voltage	V_{IL4}		0	–	0.8	V
Supply voltage	V_{CC}		6.00	6.25	6.50	V
Program supply voltage	V_{PP}		12.50	12.75	13.0	V
Initial program pulse width	t_{PW}	$V_{CC} = 6.25\text{ V} \pm 0.25\text{ V}$, $V_{PP} = 12.75\text{ V} \pm 0.25\text{ V}$	0.095	0.1	0.105	ms



Note: DO: Data output (I0 to I7)
DI: Data input (I0 to I7)

Note 1: When V_{CC} power supply is turned on or after, V_{PP} must be increased.

When V_{CC} power supply is turned off or before, V_{PP} must be decreased.

Note 2: The device must not be set to the EPROM programmer or picked up from it under applying the program voltage ($12.75\text{ V} \pm 0.25\text{ V}$) to the V_{PP} pin as the device is damaged.

Note 3: Be sure to execute the recommended programming mode with the recommended programming adaptor. If a mode or an adaptor except the above, the misoperation sometimes occurs.

Electrical Characteristics

(2) TMP87PM48

Absolute Maximum Ratings

(V_{SS} = 0 V)

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage	V _{DD}		-0.3 to 6.5	V
Input voltage	V _{IN}		-0.3 to V _{DD} + 0.3	V
Output voltage	V _{OUT}		-0.3 to V _{DD} + 0.3	V
Output current (Per 1 pin)	I _{OUT1}	Ports P0, P1, P2, P4, P5, P6, P7, P8	3.2	mA
	I _{OUT2}	Port P3	30	
Output current (Total)	Σ I _{OUT1}	Ports P0, P1, P2, P4, P5, P6, P7, P8	120	mA
	Σ I _{OUT2}	Port P3	120	
Power dissipation	PD		350	mW
Soldering temperature (Time)	T _{sld}		260 (10 s)	°C
Storage temperature	T _{stg}		-55 to 125	°C
Operating temperature	T _{opr}		-40 to 85	°C

Note: The absolute maximum ratings are rated values which must not be exceeded during operation, even for an instant. Any one of the ratings must not be exceeded. If any absolute maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no absolute maximum rating value will ever be exceeded.

Recommended Operating Conditions

(V_{SS} = 0 V, T_{opr} = -40 to 85°C)

Parameter	Symbol	Pins	Conditions		Min	Max	Unit
Supply voltage	V _{DD}		f _c = 8 MHz	NORMAL1/2 modes	4.5	5.5	V
				IDLE1/2 modes			
			f _c = 4.2 MHz	NORMAL1/2 modes	2.7		
				IDLE1/2 modes			
			f _s = 32.768 kHz	SLOW mode	2.0		
				SLEEP mode			
	STOP mode						
Input high voltage	V _{IH1}	Except hysteresis input	V _{DD} ≥ 4.5 V		V _{DD} × 0.70	V _{DD}	V
	V _{IH2}	Hysteresis input			V _{DD} × 0.75		
	V _{IH3}		V _{DD} < 4.5 V	V _{DD} × 0.90			
Input low voltage	V _{IL1}	Except hysteresis input	V _{DD} ≥ 4.5 V		0	V _{DD} × 0.30	V
	V _{IL2}	Hysteresis input				V _{DD} × 0.25	
	V _{IL3}		V _{DD} < 4.5 V	V _{DD} × 0.10			
Clock frequency	f _c	XIN, XOUT	V _{DD} = 4.5 to 5.5 V	0.4	8.0	MHz	
			V _{DD} = 2.7 to 5.5 V		4.2		
	f _s	XTIN, XTOUT		30.0	34.0	kHz	

Note 1: The recommended operating conditions for a device are operating conditions under which it can be guaranteed that the device will operate as specified. If the device is used under operating conditions other than the recommended operating conditions (Supply voltage, operating temperature range, specified AC/DC values etc.), malfunction may occur. Thus, when designing products which include this device, ensure that the recommended operating conditions for the device are always adhered to.

Note 2: The condition of clock frequency is in NORMAL1/2 modes and IDLE1/2 modes.

DC Characteristics

(V_{SS} = 0 V, T_{opr} = -40 to 85°C)

Parameter	Symbol	Pins	Conditions	Min	Typ.	Max	Unit
Hysteresis voltage	V _{HS}	Hysteresis inputs	V _{DD} = 5.0 V	–	0.9	–	V
Input current	I _{IN1}	TEST	V _{DD} = 5.5 V V _{IN} = 5.5 V/0 V	–	–	± 2	μA
	I _{IN2}	Open drain ports, Tri-state ports					
	I _{IN3}	RESET, STOP					
Input resistance	R _{IN2}	RESET	V _{DD} = 5.0 V	100	220	450	kΩ
Output leakage current	I _{LO}	Sink open drain ports	V _{DD} = 5.5 V, V _{OUT} = 5.5 V	–	–	2	μA
		Tri-state ports	V _{DD} = 5.5 V, V _{OUT} = 5.5/0 V	–	–	± 2	
Output high voltage	V _{OH2}	Tri-state ports	V _{DD} = 4.5 V, I _{OH} = -0.7 mA	4.1	–	–	V
Output low voltage	V _{OL}	Except for XOUT and P3	V _{DD} = 4.5 V, I _{OL} = 1.6 mA	–	–	0.4	mA
Output low current	I _{OL3}	P3	V _{DD} = 4.5 V, V _{OL} = 1.0 V	–	20	–	mA
Supply current in NORMAL 1, 2 modes	I _{DD}		V _{DD} = 5.5 V V _{IN} = 5.3 V/0.2 V f _c = 8 MHz f _s = 32.768 kHz	–	4.75	6.4	mA
Supply current in IDLE 1, 2 modes				–	3.25	4.65	mA
Supply current in NORMAL 1, 2 modes			V _{DD} = 3.0 V, V _{IN} = 2.8 V/0.2 V V _{IN} = 4.19 MHz f _s = 32.768 kHz	–	1.87	3.2	mA
Supply current in IDLE 1, 2 modes				–	1.35	2.2	mA
Supply current in SLOW mode			V _{DD} = 3.0 V V _{IN} = 2.8 V/0.2 V f _s = 32.768 kHz	–	20	30	μA
Supply current in SLEEP mode				–	10	20	μA
Supply current in STOP mode			V _{DD} = 5.5 V V _{IN} = 5.3 V/0.2 V	–	0.5	10	μA

Note 1: Typical values show those at T_{opr} = 25°CNote 2: Input Current I_{IN1}, I_{IN3}: The current through resistor is not included, when the input resistor (pull-up or pull-down) is contained.Note 3: I_{DD} except for I_{REF}.

AD Conversion Characteristics

(V_{SS} = 0 V, V_{DD} = 2.7 to 5.5 V, T_{opr} = -40 to 85°C)

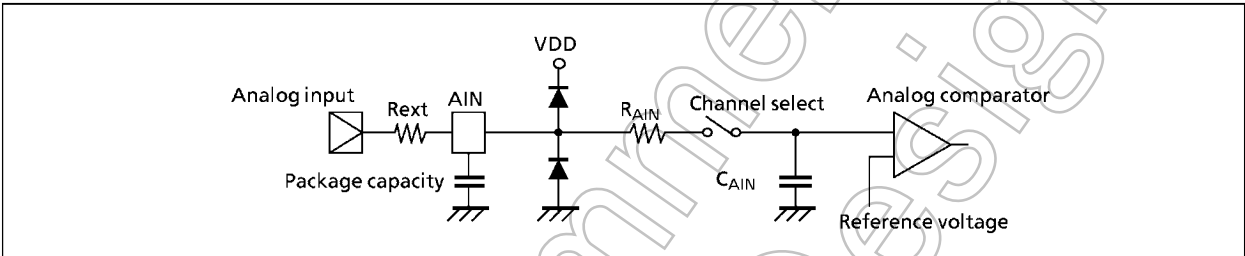
Parameter	Symbol	Conditions	Min	Typ.	Max			Unit
					ADCDR1	ADCDR2		
						ACK = 0	ACK = 1	
Analog reference voltage	V _{AREF}	V _{AREF} – V _{ASS} ≥ 2.5 V	2.7	–	V _{DD}			V
	V _{ASS}		V _{SS}	–	1.5			
Analog input voltage	V _{AIN}		V _{ASS}	–	V _{AREF}			V
Analog supply current	I _{REF}	V _{AREF} = 5.5 V, V _{ASS} = 0.0 V	–	0.5	1.2			mA
Nonlinearity error		V _{DD} = 5.0, V _{SS} = 0.0 V V _{AREF} = 5.000 V V _{ASS} = 0.000 V	–	–	± 1	± 3	± 2	LSB
Zero point error		or	–	–	± 1	± 3	± 2	
Full scale error		V _{DD} = 2.7, V _{SS} = 0.0 V V _{AREF} = 2.700 V V _{ASS} = 0.000 V	–	–	± 1	± 3	± 2	
Total error			–	–	± 2	± 6	± 4	

Note 1: ΔV_{AREF} = V_{AREF} - V_{ASS}ADCDR1: 8 bits - AD conversion result (1LSB = ΔV_{AREF}/256)ADCDR2: 10 bits - AD conversion result (1LSB = ΔV_{AREF}/1024)

Note 2: Quantizing error is not contained in those errors.

AD Input Characteristics		(Topr = - 40 to 85°C)				
Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Input impedance (Resistance)	RAIN	VDD = 5.0 V, Conversion time 23 μs (fc = 8 MHz)	—	5	—	kΩ
		VDD = 2.7 V, Conversion time 43.8 μs (fc = 4.2 MHz)	—	20	—	
Input impedance (Capacity)	CAIN	VDD = 5.0 V, Conversion time 23 μs (fc = 8 MHz)	—	7	—	pF
		VDD = 2.7 V, Conversion time 43.8 μs (fc = 4.2 MHz)	—	7	—	
Source impedance	Rext	VDD = 5.0 V, Conversion time 23 μs (fc = 8 MHz)	—	—	5	kΩ
		VDD = 2.7 V, Conversion time 43.8 μs (fc = 4.2 MHz)	—	—	5	

Note: Input current (Output leak current) error (Max ± 2 μA) and quantizing error (Max ± 4LSB) for AD are contained.



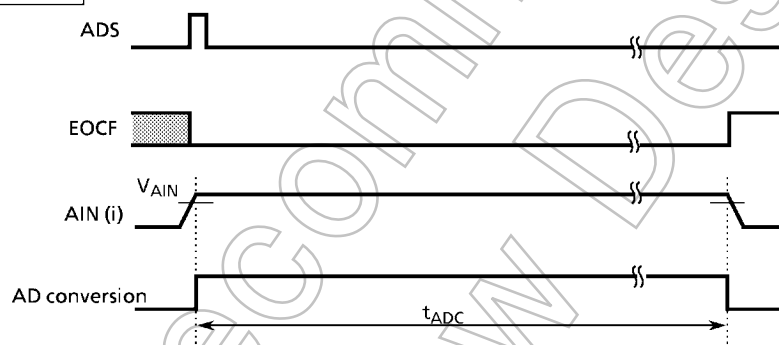
AD Pin Mode

AC Characteristics

(V_{SS} = 0 V, Topr = -40 to 85°C)

Parameter	Symbol	Conditions	V _{DD}	Min	Typ.	Max	Unit
Machine cycle time	t _{cy}	In NORMAL 1, 2 mode	4.5 to	0.5	–	10	μs
		In IDLE 1, 2 mode	5.5 V				
		In SLOW mode	2.7 to	117.6	–	133.3	
		In SLEEP mode	5.5 V				
High level clock pulse width	t _{WCH}	For external clock operation (XIN input), f _c = 8 MHz	4.5 to	62.5	–	–	ns
Low level clock pulse width	t _{WCL}		5.5 V				
High level clock pulse width	t _{WSH}	For external clock operation (XTIN input), f _s = 32.768 kHz	2.7 to	14.7	–	–	μs
Low level clock pulse width	t _{WSL}		5.5 V				
AD conversion time	t _{ADC}	ADCCR bit 4 ; ACK = 0	–	–	49 t _{cy}	–	ns
		ADCCR bit 4 ; ACK = 1	–	–	196 t _{cy}	–	

Timing of AD Conversion



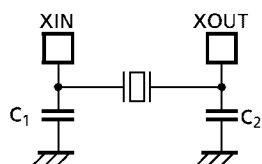
Note 1: During AD conversion, make the level of V_{AIN} stable.

Note 2: i = 17 to 10, 07 to 00

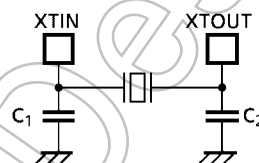
Recommended Oscillating Conditions

(V_{SS} = 0 V, Topr = -40 to 85°C)

Parameter	Oscillator	Oscillation Frequency	VDD	Recommended Oscillator	Recommended Constant	
					C ₁	C ₂
High-frequency oscillation	Ceramic resonator	8 MHz	4.5 to 5.5 V	KYOCERA KBR8.0 M	30 pF	30 pF
		4 MHz	2.7 to 5.5 V	KYOCERA KBR4.0 MS		
				MURATA CSA4.00 MG		
	Crystal oscillator	8 MHz	4.5 to 5.5 V	TOYOCOM 210B 8.0000	20 pF	20 pF
		4 MHz	2.7 to 5.5 V	TOYOCOM 204B 4.0000		
	Crystal oscillator	32.768 kHz	2.7 to 5.5 V	NDK MX-38T	15 pF	15 pF



(1) High-frequency Oscillation



(2) Low-frequency Oscillation

Note 1: When it is used in high electrical field, an electrical shield of the package is recommended to retain normal operations.

Note 2: TOYAMA MURATA MFG. CO., LTD (JAPAN)

The product numbers and specifications of the resonators by Murata Manufacturing Co., Ltd. are subject to change.

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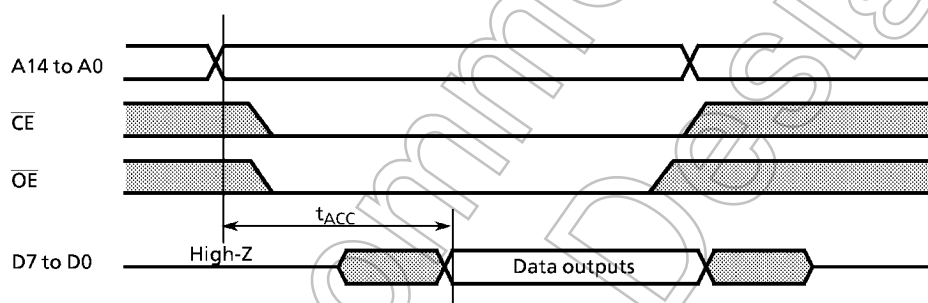
<http://www.murata.com/>

DC/AC Characteristics (PROM mode)

(V_{SS} = 0 V)

(1) Read operation

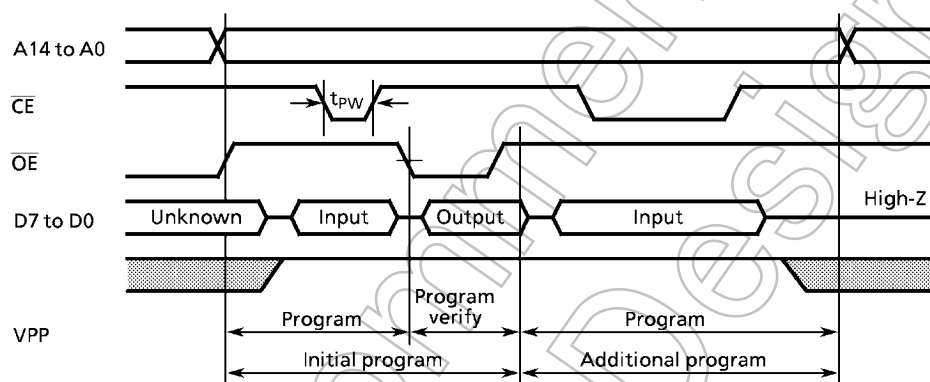
Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Input high voltage	V _{IH4}		2.2	–	V _{CC}	V
Input low voltage	V _{IL4}		0	–	0.8	V
Power supply voltage	V _{CC}		4.75	–	6.5	V
Program power supply voltage	V _{PP}					
Address access time	t _{ACC}	V _{CC} = 5.0 ± 0.25 V	–	1.5 t _{cy} + 300	–	ns

Note: t_{cy} = 500 ns at 8 MHz

Timing Waveforms of Read Operation

(2) Program Operation (High-speed write mode - I) (Topr = 25 ± 5°C)

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Input high voltage	V_{IH4}		2.2	—	V_{CC}	V
Input low voltage	V_{IL4}		0	—	0.8	V
Power supply voltage	V_{CC}		5.75	6.0	6.25	V
Program power supply voltage	V_{PP}		12.0	12.5	13.0	V
Initial program pulse width	t_{PW}	$V_{CC} = 6.0\text{ V} \pm 0.25\text{ V}$, $V_{PP} = 12.5 \pm 0.5\text{ V}$	0.95	1.0	1.05	ms

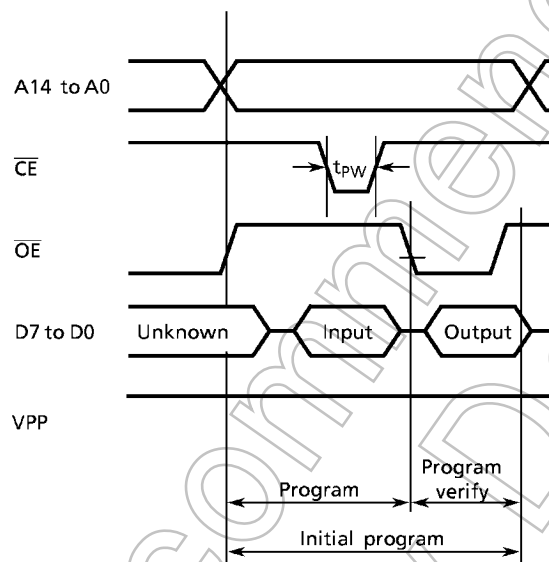


Timing Waveforms of Programming Operation

- Note 1:** When V_{CC} power supply is turned on or after, V_{PP} must be increased.
When V_{CC} power supply is turned off or before, V_{PP} must be decreased.
- Note 2:** The device must not be set to the EPROM programmer or picked up from it under applying the program voltage ($12.5\text{ V} \pm 0.5\text{ V}$) to the V_{PP} pin as the device is damaged.
- Note 3:** Be sure to execute the recommended programming mode with the recommended programming adaptor. If a mode or an adaptor except the above, the misoperation sometimes occurs.

(3) Program operation (High-speed write mode - II) ($T_{opr} = 25 \pm 5^{\circ}\text{C}$)

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Input high voltage	V_{IH4}		2.2	–	V_{CC}	V
Input low voltage	V_{IL4}		0	–	0.8	V
Supply voltage	V_{CC}		6.00	6.25	6.50	V
Program supply voltage	V_{PP}		12.50	12.75	13.0	V
Initial program pulse width	t_{PW}	$V_{CC} = 6.25\text{ V} \pm 0.25\text{ V}$, $V_{PP} = 12.75\text{ V} \pm 0.25\text{ V}$	0.095	0.1	0.105	ms



Note 1: When V_{CC} power supply is turned on or after, V_{PP} must be increased.

When V_{CC} power supply is turned off or before, V_{PP} must be decreased.

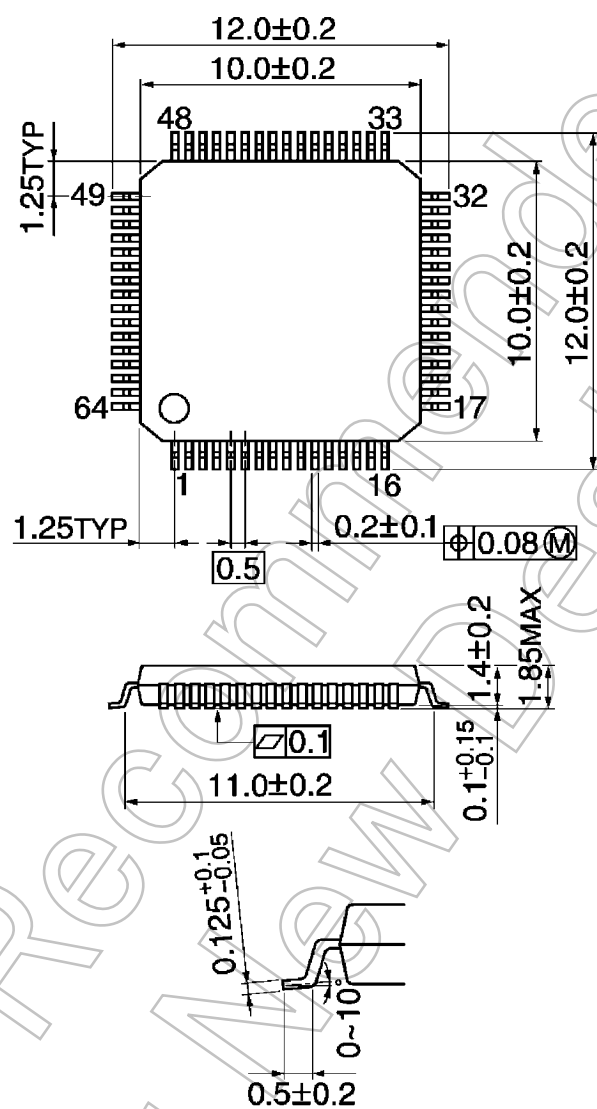
Note 2: The device must not be set to the EPROM programmer or picked up from it under applying the program voltage ($12.75\text{ V} \pm 0.25\text{ V}$) to the V_{PP} pin as the device is damaged.

Note 3: Be sure to execute the recommended programming mode with the recommended programming adaptor. If a mode or an adaptor except the above, the misoperation sometimes occurs.

Package Dimensions

P-LQFP64-1010-0.50

Unit: mm



Not Recommended
for New Design